SEMICONDUCTOR PACKAGE AND METHOD OF MAKING THE SAME

ABSTRACT OF THE DISCLOSURE

A stiffener is provided for use in making semiconductor devices. The stiffener and method of use provided prevent or reduce warpage of a semiconductor package during the assembly process. More particularly, the stiffener functions to prevent or reduce warpage during molding of an assembly of wafers and/or dies. The stiffener may be positioned above the backside or non-active side of an assembly of wafer and/or dies during molding. The presence of the stiffener prevents or reduces warpage caused by CTE mismatch between the mold material and the wafer and/or under the high temperatures encountered in the process of molding. After molding, the stiffener may continue to provide support to the assembly.

FIG. 1(P)